Product / Package Information

Package	LFCSP - Side Solderable
Body Size (mm)	7 X 7 X 0.75 (5.6 EP)
Lead Count	48
Terminal Finish	100 Sn
MS Number	MS011012B

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.86E-02	86.2	862000	34.32	343246
Thermosets	Epoxy resin	Proprietary	2.69E-03	6.0	60000	2.39	23892
Thermosets	Phenol resin	Proprietary	2.69E-03	6.0	60000	2.39	23892
Other inorganic materials	Metal Hydroxide	Proprietary	6.71E-04	1.5	15000	0.60	5973
Other inorganic materials	Carbon black	1333-86-4	1.34E-04	0.3	3000	0.12	1195
Subtotal			4.48 E-02	100.00	1000000	39.82	398197

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.49 E-02	97.5	975000	48.87	488696
Copper & its alloys	Iron	7439-89-6	1.32 E-03	2.35	23500	1.18	11779
Copper & its alloys	Zinc	7440-66-6	6.76 E-05	0.12	1200	0.06	601
Copper & its alloys	Phosphorus	7723-14-0	1.69 E-05	0.03	300	0.02	150
Subtotal			5.63 E-02	100.00	1000000	50.12	501226

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.63 E-04	100.0	1000000	0.50	5012

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.39 E-04	100.0	1000000	0.12	1234

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	6.06 E-04	100.0	1000000	0.54	5389

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	8.45 E-03	100.0	1000000	7.52	75205

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.14 E-03	73.54	735400	1.01	10102
Other organic materials	Epoxy resin A	TS ref# 10013	1.13 E-04	7.35	73500	0.10	1010
Others	Anhydride	TS ref# 10181	1.13 E-04	7.35	73500	0.10	1010
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	4.54 E-05	2.94	29400	0.04	404
Other organic materials	Epoxy resin B	TS ref# 10237	4.54 E-05	2.94	29400	0.04	404
Others	Epoxy resin modifier	TS ref# 10038	4.54 E-05	2.94	29400	0.04	404
Others	Anhydride	TS ref# 10180	4.54 E-05	2.94	29400	0.04	404
Subtotal			1.54 E-03	100.0	1000000	1.37	13737

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.12 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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